

ABSTRACT

It is an object of the invention to provide a curable resin composition excellent in mechanical strength, heat
5 resistance, moisture resistance, flexibility, resistance to thermal cycles, resistance to solder reflow, dimensional stability, and the like after curing and providing high adhesion reliability and conduction reliability and an adhesive epoxy resin paste, an adhesive epoxy resin sheet,
10 a conductive connection paste, and a conductive connection sheet using the curable resin composition, and an electronic component joined body.

The invention relates to a curable resin composition, which contains an epoxy resin, a solid polymer having a
15 functional group to react with the epoxy group and a curing agent for an epoxy resin, no phase separation structure being observed in a matrix of a resin when a cured product is dyed with a heavy metal and observed with a transmission electron microscope.